Step-up DC / DC Converter with Overcurrent Protection

NO.EA-272-201211

OUTLINE

The R1205x is a PWM control type step-up DC/DC converter IC with low supply current. Each of these ICs consists of an NMOS FET, a diode, an oscillator, a PWM comparator, a voltage reference unit, an error amplifier, a current limit circuit, an under voltage lockout circuit (UVLO), an over-voltage protection circuit (OVP), a soft-start circuit, a Maxduty limit circuit, and a thermal shutdown protection circuit. This step-up DC/DC converter can be easily built with a few external components such as a coil, a resistor, and a capacitor. As the protection functions, the R1205x has an Lx peak current limit function, an over voltage protection (OVP) function, an under voltage lock out (UVLO) function and a thermal shutdown function.
The R1205x presents the R1205x8xxA version that is optimized for the constant voltage power source, and the R1205x8xxB/C version that is optimized for driving the white LED with the constant current. The R1205x8xxB/C is an adjustable version that can change the LED brightness dynamically by using a 200Hz to 300kHz PWM signal toward the CE pin.
The R1205x is available in DFN1616-6B and TSOT-23-6 packages.

FEATURES

- Input Voltage Range .... 2.3V to 5.5V (R1205x8xxA)
  1.8V to 5.5V (R1205x8xxB/C)
- Supply Current .... Typ. 800μA
- Standby Current .... Max. 5μA
- Feedback Voltage .... 1.0V±15mV (R1205x8xxA)
  0.2V±10mV (R1205x8xxB)
  0.4V±10mV (R1205x8xxC)
- Oscillator Frequency .... Typ. 1.2MHz
- Maximum Duty Cycle .... Typ. 91%
- UVLO Function Typ.2.0V (Hys.Typ.0.2V) (R1205x8xxA)
  Typ.1.6V (Hys.Typ.0.1V) (R1205x8xxB/C)
- Selectable Lx Current Limit Function.................... Typ. 350mA / 700mA
- Over Voltage Protection .... Typ. 25V
- LED dimming control (R1205x8xxB/C) ....by external PWM signal (Frequency 200Hz to 300kHz)
- Thermal Protection Function................................ Typ.150ºC(Hys.Typ.50ºC)
- Switch ON Resistance .... Typ. 1.35Ω
- Packages DFN1616-6B, TSOT-23-6
- Ceramic capacitors are recommended

APPLICATION

- Constant Voltage Power Source for portable equipment
- OLED power supply for portable equipment
- White LED Backlight for portable equipment

SELECTION GUIDE

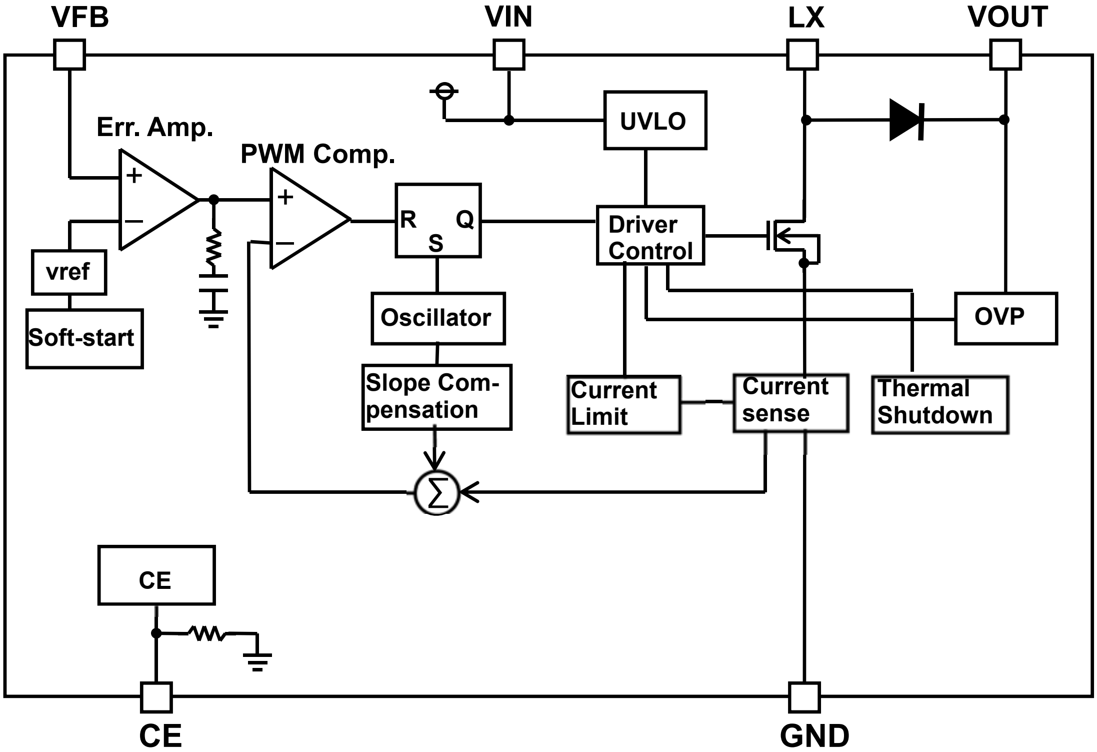
The OVP threshold voltage, current limit, package and V_{FB}/Auto discharge are user-selectable options.

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
R1205L8x1∗-TR	DFN1616-6B	5,000 pcs	Yes	Yes
R1205N8x3∗-TR-FE	TSOT-23-6	3,000 pcs	Yes	Yes

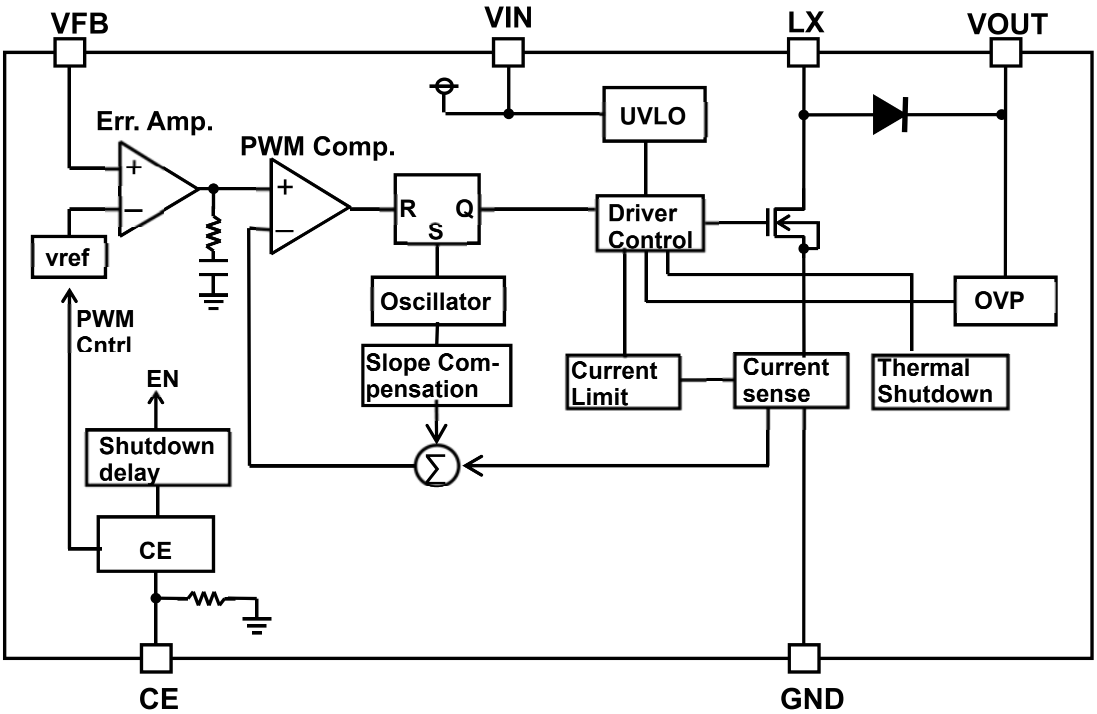
x : Designation of current limit.
(1) 350mA
(2) 700mA

∗ : Designation of VFB.
(A) 1.0V
(B) 0.2V
(C) 0.4V

BLOCK DIAGRAMS



R1205x8xxA

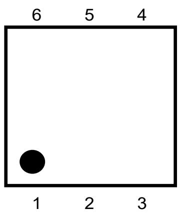


R1205x8xxB/C

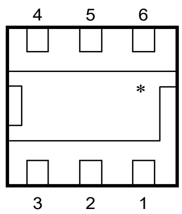
PIN DESCRIPTIONS

DFN1616-6B

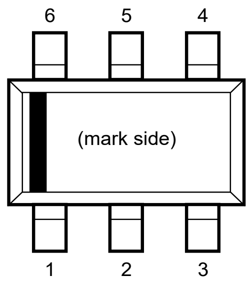
Top View



Bottom View



TSOT-23-6



DFN1616-6B

Pin No	Symbol	Pin Description
1	CE	Chip Enable Pin ("H" Active)
2	VFB	Feedback Pin
3	LX	Switching Pin (Open Drain Output)
4	GND	Ground Pin
5	VIN	Input Pin
6	VOUT	Output Pin

∗ The tab is substrate level (GND). The tab is better to be connected to the GND, but leaving it open is also acceptable.

TSOT-23-6

Pin No	Symbol	Pin Description
1	CE	Chip Enable Pin ("H" Active)
2	VOUT	Output Pin
3	VIN	Input Pin
4	LX	Switching Pin (Open Drain Output)
5	GND	Ground Pin
6	VFB	Feedback Pin

ABSOLUTE MAXIMUM RATINGS

GND=0V

Symbol	Item		Rating	Unit
V_{IN}	VIN Pin Voltage		–0.3 to 6.5	V
V_{CE}	CE Pin Voltage		–0.3 to 6.5	V
V_{FB}	VFB Pin Voltage		–0.3 to 6.5	V
V_{OUT}	VOUT Pin Voltage		–0.3 to 28	V
V_{LX}	LX Pin Voltage		–0.3 to 28	V
I_{LX}	LX Pin Current		1000	mA
P_D	Power Dissipation [1]	DFN1616-6B (JEDEC STD. 51-7 Test Land Pattern)	2400	mW
		TSOT-23-6 (Standard Test Land Pattern)	460	
Tj	Junction Temperature Range		–40 to 125	°C
Tstg	Storage Temperature Range		–55 to 125	°C

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the life time and safety for both device and system using the device in the field.
The functional operation at or over these absolute maximum ratings are not assured.

RECOMMENDED OPERATING CONDITIONS

Symbol	Item	Rating	Unit
V_{IN}	Input Voltage (R1205x8xxA)	2.3 to 5.5	V
	Input Voltage (R1205x8xxB/C)	1.8 to 5.5	
Ta	Operating Temperature Range	−40 to 85	°C

RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such ratings by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

[1] Refer to *POWER DISSIPATION* for detailed information.

ELECTRICAL CHARACTERISTICS

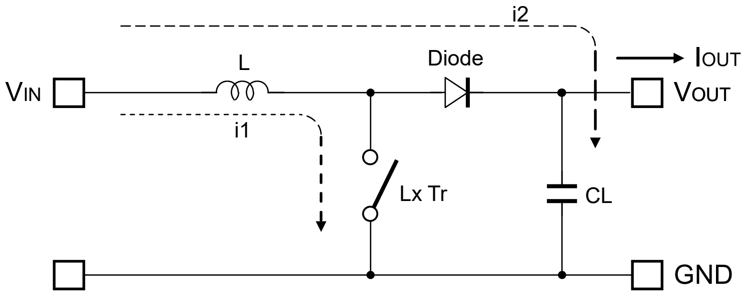
R1205x (Ta=25°C)

Symbol	Item	Conditions		Min.	Typ.	Max.	Unit
I_{DD}	Supply Current	V_{IN}=5.5V, V_{FB}=0V , L_X at no load			0.8	1.2	mA
$I_{standby}$	Standby Current	V_{IN}=5.5V, V_{CE}=0V			1.0	5.0	μA
V_{UVLO1}	UVLO Detector Threshold	V_{IN} falling	R1205x8xxA	1.9	2.0	2.1	V
			R1205x8xxB/C	1.5	1.6	1.7	
V_{UVLO2}	UVLO Released Voltage	V_{IN} rising	R1205x8xxA		V_{UVLO1} +0.2	2.3	V
			R1205x8xxB/C		V_{UVLO1} +0.1	1.8	
V_{CEH}	CE Input Voltage "H"	V_{IN}=5.5V		1.5			V
V_{CEL}	CE Input Voltage "L"					0.5	V
R_{CE}	CE Pull Down Resistance				1200		kΩ
V_{FB}	V_{FB} Voltage Accuracy	V_{IN}=3.6V	R1205x8xxA	0.985	1.000	1.015	V
			R1205x8xxB	0.19	0.2	0.21	
			R1205x8xxC	0.39	0.4	0.41	
$\Delta V_{FB}/\Delta Ta$	V_{FB} Voltage Temperature Coefficient	V_{IN}=3.6V, $-40°C \leq Ta \leq 85°C$			±150		ppm /°C
I_{FB}	V_{FB} Input Current	V_{IN}=5.5V, V_{FB}=0V or 5.5V		-0.1		0.1	μA
t_{start}	Soft-start Time		R1205x8xxA		2.0	3.0	ms
R_{ON}	FET ON Resistance	I_{LX}=100mA			1.35		Ω
I_{OFF}	FET Leakage Current	V_{LX}=24V				3.0	μA
I_{LIM}	FET Current Limit		R1205x81xx	250	350	450	mA
			R1205x82xx	500	700	900	
V_F	Diode Forward Voltage	I_{SW}=100mA			0.8		V
$I_{DIODEleak}$	Diode Leakage Current	V_{OUT}=24V, V_{LX}=0V				10	μA
f_{osc}	Oscillator Frequency	V_{IN}=3.6V, V_{FB}=0V		1000	1200	1400	kHz
Maxduty	Maximum Duty Cycle	V_{IN}=3.6V, V_{FB}=0V		86	91		%
V_{OVP1}	OVP Detect Voltage	V_{IN}=3.6V, V_{OUT} rising		24.2	25	25.8	V
V_{OVP2}	OVP Release Voltage	V_{IN}=3.6V, V_{OUT} falling			V_{OVP1} -1.8		V
T_{TSD}	Thermal Shutdown Detect Temperature	V_{IN}=3.6V			150		°C
T_{TSR}	Thermal Shutdown Release Temperature	V_{IN}=3.6V			100		°C

THEORY OF OPERATION

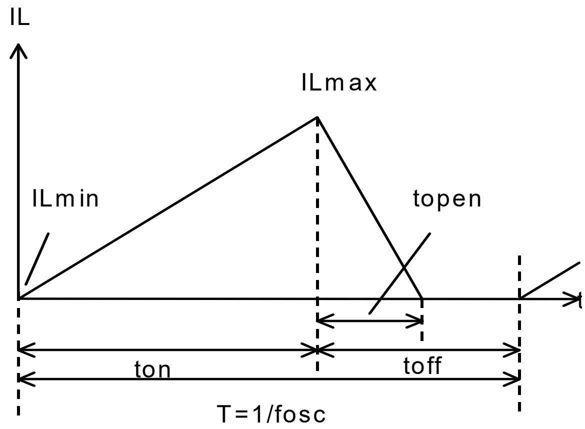
Operation of Step-Up DC/DC Converter and Output Current

<Basic Circuit>

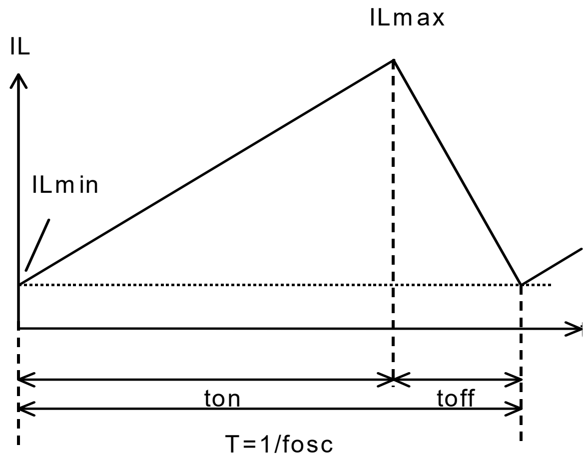


<Current through L>

Discontinuous mode



Continuous mode



There are two operation modes of the step-up PWM control-DC/DC converter. That is the continuous mode and discontinuous mode by the continuousness inductor.

When the transistor turns ON, the voltage of inductor L becomes equal to V_{IN} voltage. The increase value of inductor current (i1) will be

$\Delta i1 = V_{IN} \times t_{on} / L$ .... Formula 1

As the step-up circuit, during the OFF time (when the transistor turns OFF) the voltage is continually supply from the power supply. The decrease value of inductor current (i2) will be

$\Delta i2 = (V_{OUT} - V_{IN}) \times t_{open} / L$ .... Formula 2

At the PWM control-method, the inductor current become continuously when $t_{open}=t_{off}$, the DC/DC converter operate as the continuous mode.

In the continuous mode, the variation of current of i1 and i2 is same at regular condition.

$V_{IN} \times t_{on} / L = (V_{OUT} - V_{IN}) \times t_{off} / L$ .... Formula 3

The duty at continuous mode will be

$duty (\%) = t_{on} / (t_{on} + t_{off}) = (V_{OUT} - V_{IN}) / V_{OUT}$ .... Formula 4

The average of inductor current at tf = t_{off} will be

$IL(Ave.) = V_{IN} \times t_{on} / (2 \times L)$ .... Formula 5

If the input voltage = output voltage, the I_{OUT} will be

$I_{OUT} = V_{IN}^2 \times t_{on} / (2 \times L \times V_{OUT})$ .... Formula 6

If the I_{OUT} value is large than above the calculated value (Formula 6), it will become the continuous mode, at this status, the peak current (IL_{max}) of inductor will be

$IL_{max} = I_{OUT} \times V_{OUT} / V_{IN} + V_{IN} \times t_{on} / (2 \times L)$ .... Formula 7

$IL_{max} = I_{OUT} \times V_{OUT} / V_{IN} + V_{IN} \times T \times (V_{OUT} - V_{IN}) / (2 \times L \times V_{OUT})$ .... Formula 8

The peak current value is larger than the I_{OUT} value. In case of this, selecting the condition of the input and the output and the external components by considering of IL_{max} value.
The explanation above is based on the ideal calculation, and the loss caused by L_X switch and the external components are not included.
The actual maximum output current will be between 50% and 80% by the above calculations. Especially, when the IL is large or V_{IN} is low, the loss of V_{IN} is generated with on resistance of the switch. Moreover, it is necessary to consider V_f of the diode (approximately 0.8V) about V_{OUT}.

Soft-Start (R1205x8xxA)

The output and referrence of the error amplifier start from 0V and the referrence gradually rises up to 1.0V. After the softstart time (TSS), output voltage rise up to the setting voltage.
The output of the error amplifier starts from 0V and the inrush current is suppressed when starting by the CE pin "H" input. Moreover, the inrush current can be suppressed by gradually enlarging Duty of the PWM signal to the CE pin.

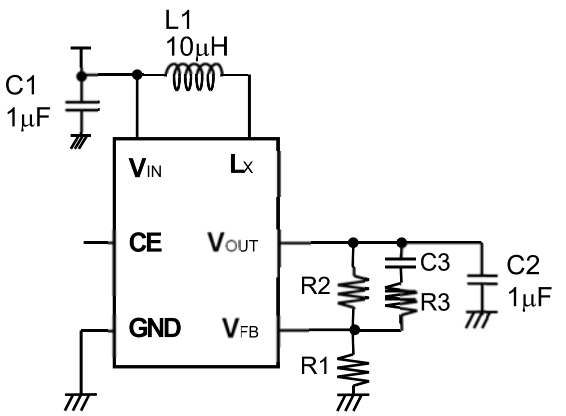
Current Limit Function

Current limit function monitors the over current and if it reaches the peak current, it will turn off the driver. When the over current decreases, it will restart oscillation and will restart the monitoring.

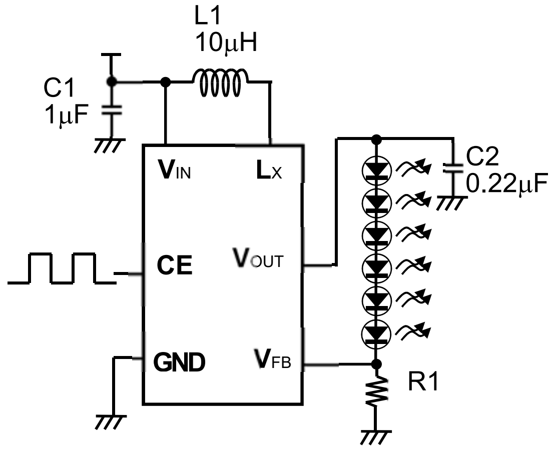
APPLICATION INFORMATION

Typical Applications

R1205x8xxA



R1205x8xxB/C



Inductor Selection

The peak current of the inductor at normal mode can be estimated as the next formula when the efficiency is 80%.

$$IL_{max} = 1.25 \times I_{OUT} \times V_{OUT} / V_{IN} + 0.5 \times V_{IN} \times (V_{OUT} - V_{IN}) / (L \times V_{OUT} \times f_{osc})$$

In the case of start-up or dimming control by CE pin, inductor transient current flows, and the peak current of it must be equal or less than the current limit of the IC. The peak current should not beyond the rated current of the inductor.
The recommended inductance value is 10μH - 22μH.

Table 1 Peak current value in each condition

Condition				
V_{IN} (V)	V_{OUT} (V)	I_{OUT} (mA)	L (μH)	IL_{max} (mA)
3	14	20	10	215
3	14	20	22	160
3	21	20	10	280
3	21	20	22	225

Table 2 Recommended inductors

L (μH)	Part No.	Rated Current (mA)	Size (mm)
10	LQH32CN100K53	450	3.2x2.5x1.55
10	LQH2MC100K02	225	2.0x1.6x0.9
10	VLF3010A-100	490	2.8x2.6x0.9
10	VLS252010-100	520	2.5x2.0x1.0
22	LQH32CN220K53	250	3.2x2.5x1.55
22	LQH2MC220K02	185	2.0x1.6x0.9
22	VLF3010A-220	330	2.8x2.6x0.9

Capacitor Selection

Set 1μF or more value bypass capacitor C1 between V_{IN} pin and GND pin as close as possible.

R1205xxxxA
Set 1μF – 4.7μF or more capacitor C2 between V_{OUT} and GND pin.

Table 3-A Recommended components for R1205xxxxA

	Rated voltage(V)	Part No.
C1	6.3	CM105B105K06
C2	25	GRM21BR11E105K
C3	25	22pF
R1		For V_{OUT} Setting
R2		For V_{OUT} Setting
R3		2kΩ

If the transient drop of output voltage by the load fluctuation is large and exceeds the allowable range in above setting, refer to Table 3-B to change the capacitors of C2 and C3 for the response improvement and the transient voltage drop reduction.

Table 3-B Recommended components for R1205xxxxA

	Rated voltage(V)	Part No.
C1	6.3	CM105B105K06
C2	50	GRM31CR71H475M
C3	25	220pF
R1		For V_{OUT} Setting
R2		For V_{OUT} Setting
R3		2kΩ

R1205xxxxB/C
Set 0.22μF or more capacitor C2 between V_{OUT} and GND pin. (R1205x8xxB)
Set 0.47μF or more capacitor C2 between V_{OUT} and GND pin. (R1205x8xxC)
Note the V_{OUT} that depends on LED used, and select the rating of V_{OUT} or more.

Table 4 Recommended components for R1205xxxxB/C

	Rated voltage(V)	Part No.
C1	6.3	CM105B105K06
C2	25	GRM21BR11E224
	25	C2012X7R1E474K
	50	GRM21BR71H224

External Components Setting

If the V_{OUT} spike noise is high, it may influence on the V_{FB} pin to cause the operation of R1205x8xxA unstable. To reduce the noise coming into V_{FB} pin, please place a 1kΩ to 5kΩ resistor in R3 in Fig. 1.

Application of Using 5.5V or more Power Supply

Other than the IC power supply, if there is a power supply greater than 5.5V, the high power output can be achieved by using the power supply as an inductor power supply. In this case, please place a capacitor between an inductor power supply and GND (shown in Fig. 2) aside from a bypass capacitor between the V_{IN} pin and GND of the IC.

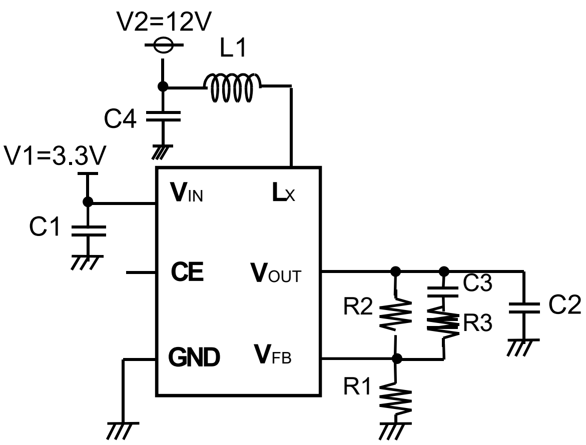


Fig. 1 R1205x8xxA

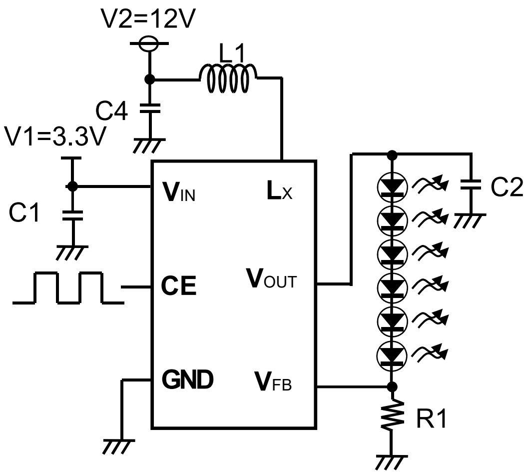


Fig .2 R1205x8xxB/C

The Method of Output Voltage Setting (R1205x8xxA)

The output voltage (V_{OUT}) can be calculated with divider resistors (R1 and R2) values as the following formula:

$$\text{Output Voltage } (V_{OUT}) = V_{FB} \times (R1 + R2) / R1$$

The total value of R1 and R2 should be equal or less than 300kΩ. Make the V_{IN} and GND line sufficient. The large current flows through the V_{IN} and GND line due to the switching. If this impedance (V_{IN} and GND line) is high, the internal voltage of the IC may shift by the switching current, and the operating may become unstable. Moreover, when the built-in L_X switch is turn OFF, the spike noise caused by the inductor may be generated.

LED Current setting (R1205x8xxB/C)

When CE pin input is "H" (Duty=100%), LED current can be set with feedback resistor (R1)

$$I_{LED} = V_{FB} / R1$$

LED Dimming Control (R1205x8xxB/C)

The LED brightness can be controlled by inputting the PWM signal to the CE pin. If the CE pin input is "L" in the fixed time (Typ.0.5ms), the IC becomes the standby mode and turns OFF LEDs.

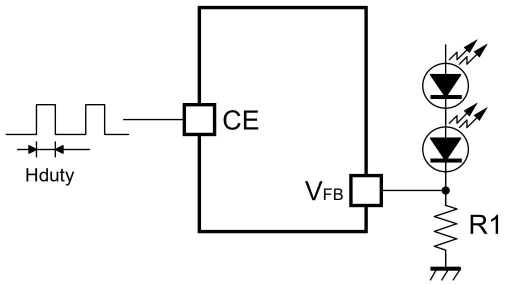
The current of LEDs can be controlled by Duty of the PWM signal of the input CE pin. The current of LEDs when High-Duty of the CE input is "Hduty" reaches the value as calculatable following formula.

$$I_{LED} = Hduty \times V_{FB} / R1$$

The frequency of the PWM signal is using the range between 200Hz to 300kHz.

When controlling the LED brightness by the PWM signal of 5kHz or less, R1205x8xxB/C are recomended to avoide discharge function during dimming control.

When controlling the LED brightness by the PWM signal of 20kHz or less, the increasing or decreasing of the inductor current might be make a sounds in the hearable sound wave area. In that case, please use the PWM signal in the high frequency area.



Dimming Control by CE Pin Input

I_{LED} accuracy (R1205x8xxB / R1205x8xxC)

LED current (I_{LED}) is affected by the offset voltage of the error amplifier in the DC/DC converter.

LED might turn off due to the offset voltage variation, when brightness is controlled by low PWM duty cycle.

In case of R1205x8xxB, it is recommended to input PWM signal that has 18.5% or more duty.

In case of lower duty cycle than 18.5%, it is recommended to use R1205x8xxC.

The table below shows the I_{LED} accuracy of R1205x8xxC at low PWM duty cycle input (low brightness).

I_{LED} accuracy when low PWM Duty is applied (R1 = 20 Ω)

	PWM Duty applied to CE Pin	I_{LED} Min.	I_{LED} Max.
R1205x8xxC	3.5% (Frequency = 20kHz to 300kHz)	0.01mA[1]	2.1mA[1]

[1] Design guaranteed value (Ta = 25 ºC)

TECHNICAL NOTES

● Current Path on PCB

The current paths in an application circuit are shown in Fig. 3 and 4.
A current flows through the paths shown in Fig. 3 at the time of MOSFET-ON, and shown in Fig. 4 at the time of MOSFET-OFF. In the paths pointed with red arrows in Fig. 4, current flows just in MOSFET-ON period or just in MOSFET-OFF period. Parasitic impedance / inductance and the capacitance of these paths influence stability of the system and cause noise outbreak. So please minimize this side effect. In addition, please shorten the wiring of other current paths shown in Fig. 3 and 4 except for the paths of LED load.

● Layout Guide for PCB

・Please shorten the wiring of the input capacitor (C1) between V_{IN} pin and GND pin of IC. The GND pin should be connected to the strong GND plane.

・The area of L_X land pattern should be smaller.

・Please put output capacitor (C2) close to the V_{OUT} pin.

・Please make the GND side of output capacitor (C2) close to the GND pin of IC.

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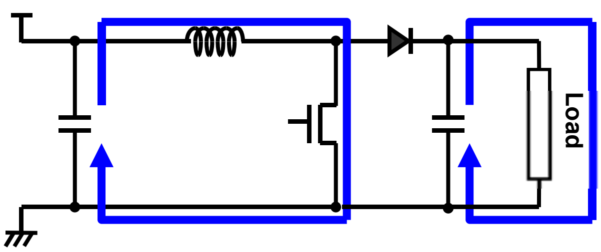


Fig. 3 MOSFET-ON

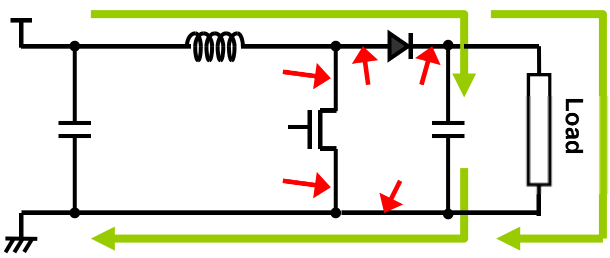
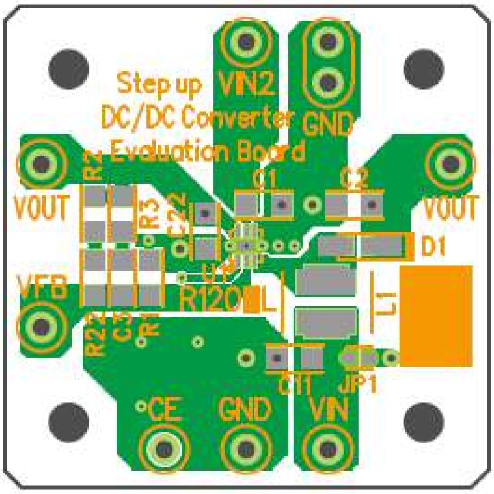
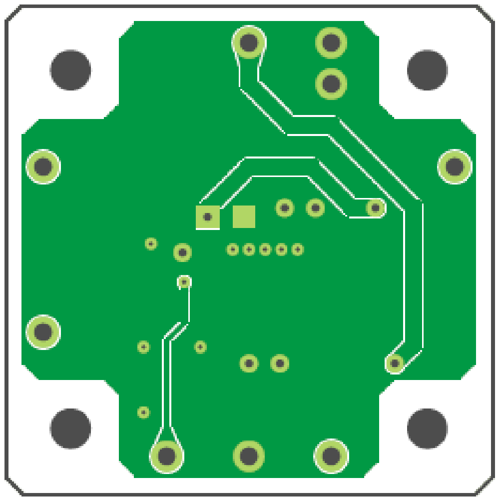


Fig. 4 MOSFET-OFF

● **PCB Layout**

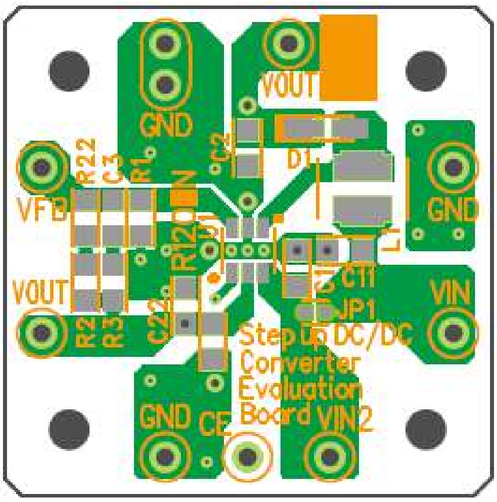
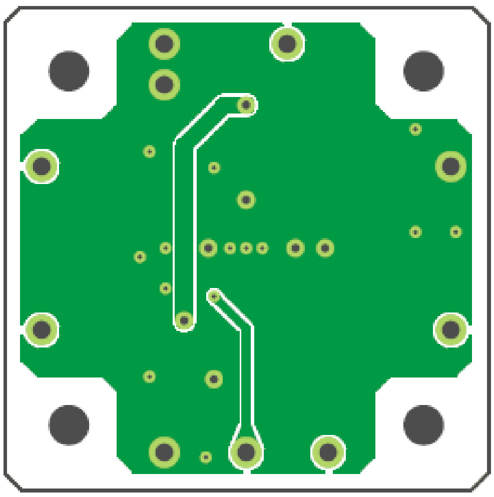
PKG: DFN1616-6B pin

R1205LxxxA/xxxB/xxxC Typical Board Layout

Top Layer	Back Layer
	

・**PKG:TSOT-23-6pin**

R1205NxxxA/xxxB/xxxCTypical Board Layout

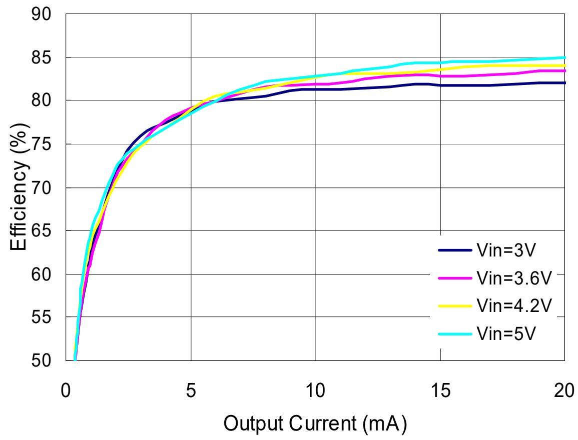
Top Layer	Back Layer
	

U1-● indicates the position of No.1 pin.

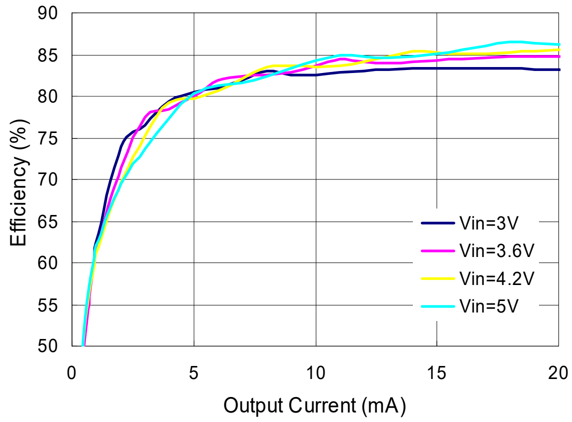
TYIPICAL CHARACTERISTICS

1) Efficiency vs. Output Current Characteristics (R1205N823A)

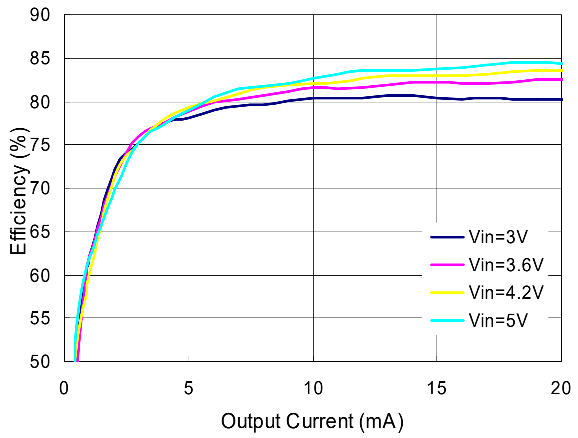
V_{OUT}=10V, L=10μH (LQH32CN100K53)



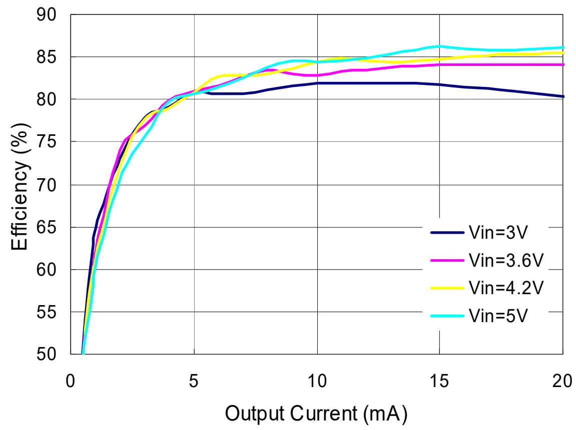
V_{OUT}=10V, L=22μH (LQH32CN220K53)



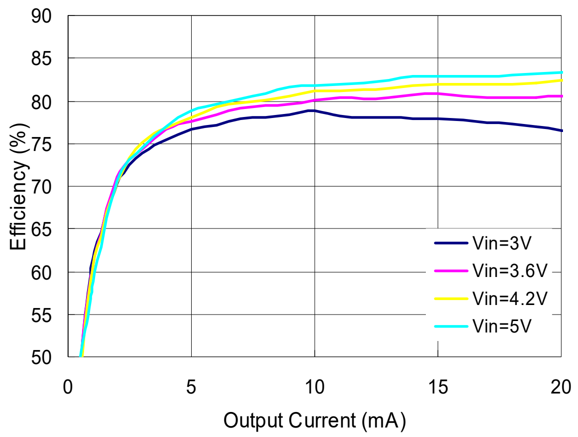
V_{OUT}=15V, L=10μH (LQH32CN100K53)



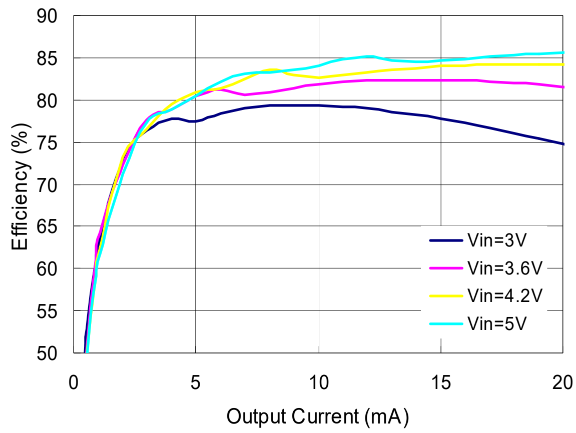
V_{OUT}=15V, L=22μH (LQH32CN220K53)



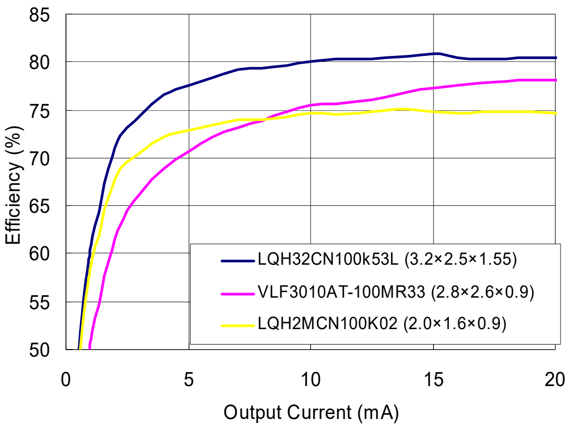
V_{OUT}=20V, L=10μH (LQH32CN100K53)



V_{OUT}=20V, L=22μH (LQH32CN220K53)

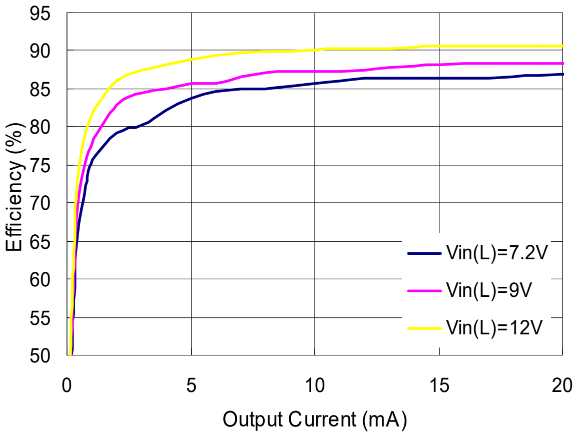


V_{OUT}=20V, V_{IN}=3.6V

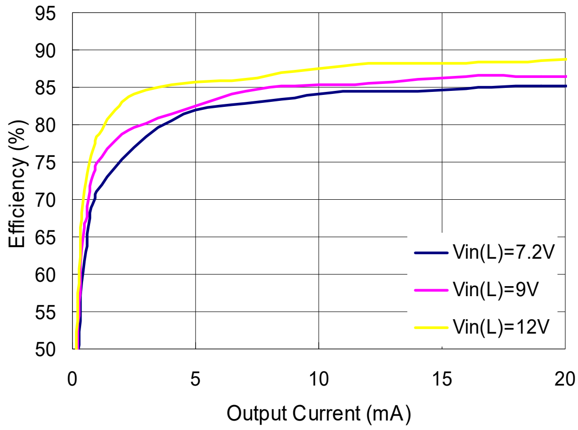


Typical Applications with Using 5.5V or Greater

V_{OUT}=15V, L=10µH (LQH32CN100K53)

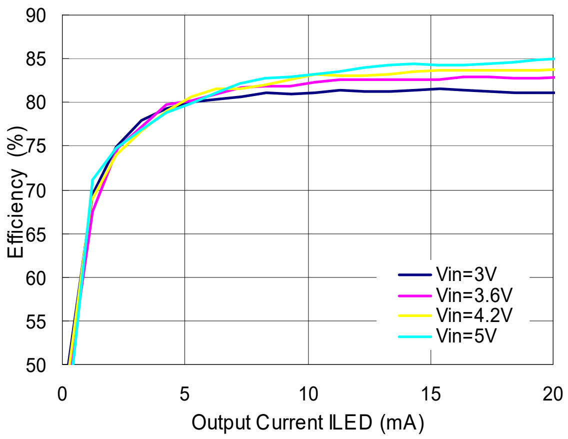


V_{OUT}=20V, L=10µH (LQH32CN100K53)

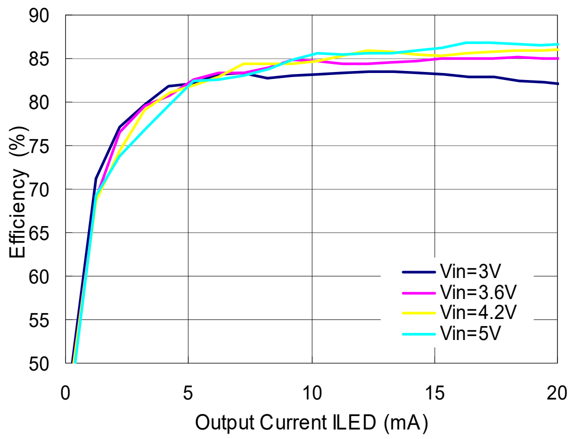


2) Efficiency vs. Output Current Characteristics (R1205N823B/C)

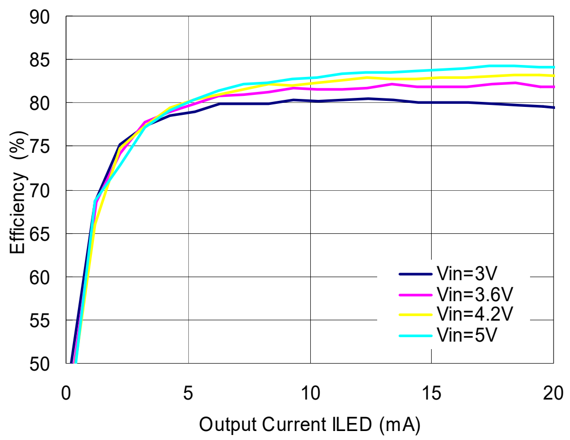
4LED, L=10µH (LQH32CN100K53)



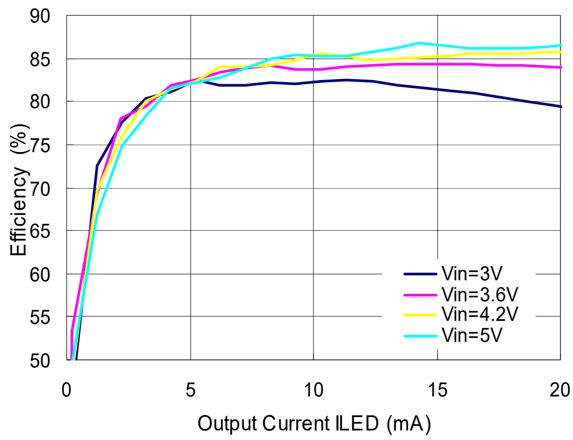
4LED, L=22µH (LQH32CN220K53)



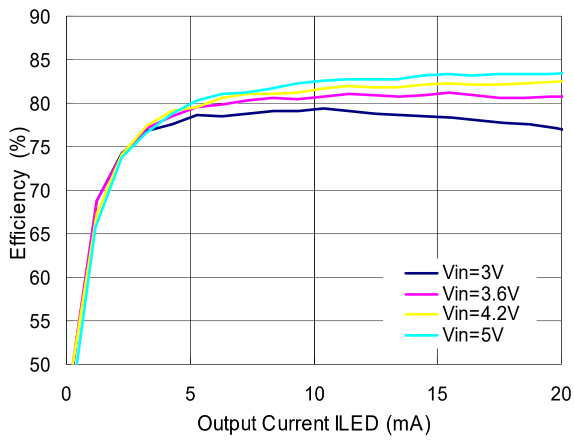
5LED, L=10µH (LQH32CN100K53)



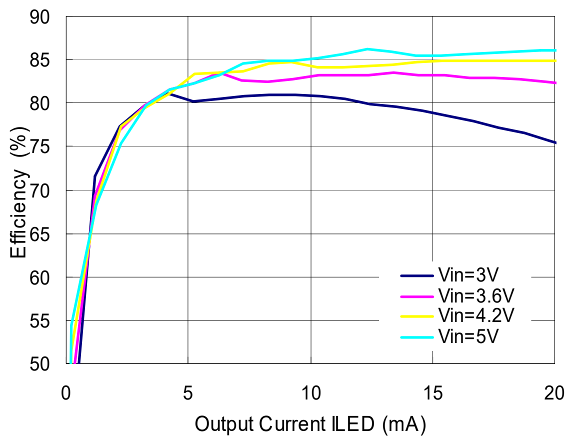
5LED, L=22µH (LQH32CN220K53)



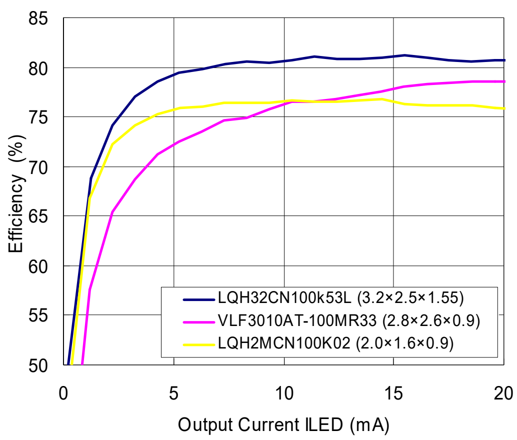
6LED, L=10µH (LQH32CN100K53)



6LED, L=22µH (LQH32CN220K53)

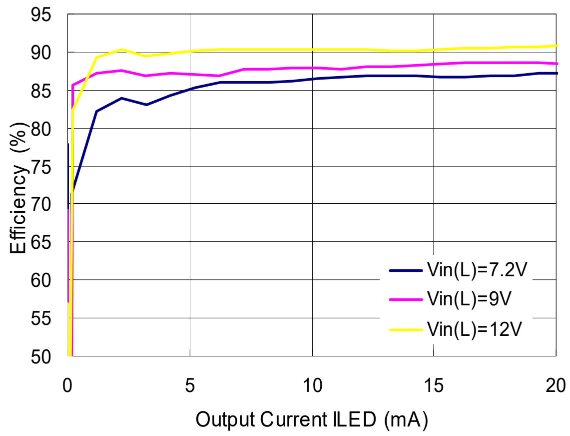


6LED, V_{IN}=3.6V

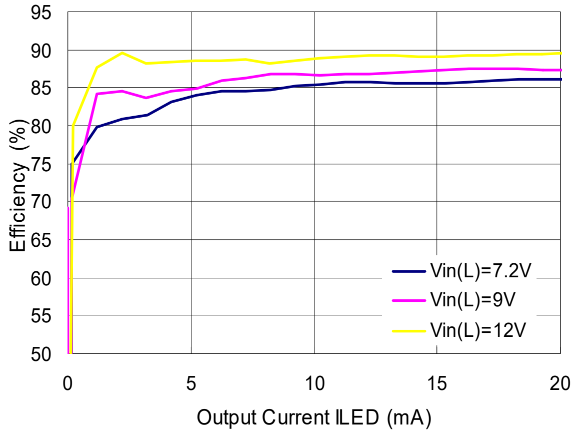


Typical Applications with Using 5.5V or Greater

5LED, V_{IN}(IC)=3.6V

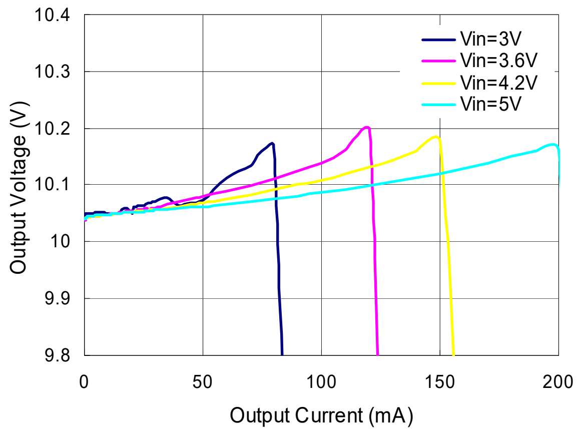


6LED, V_{IN}(IC)=3.6V

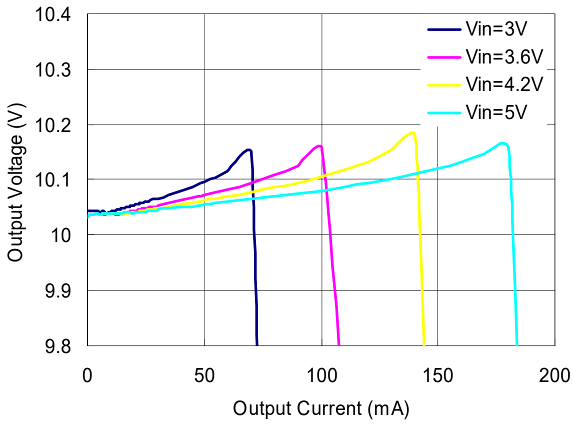


3) Output Voltage vs. Output Current (R1205N823A)

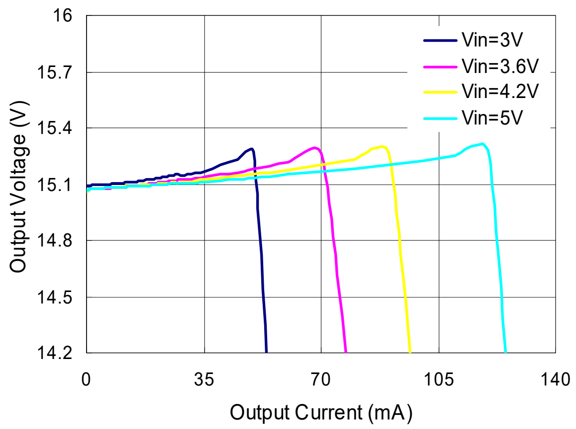
V_{OUT}=10V, L=10μH (LQH32CN100K53)



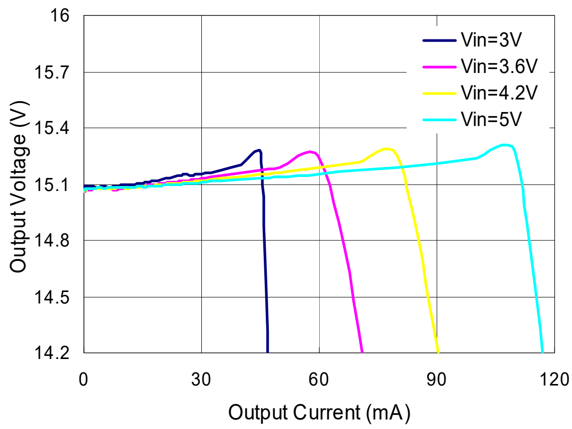
V_{OUT}=10V, L=22μH (LQH32CN220K53)



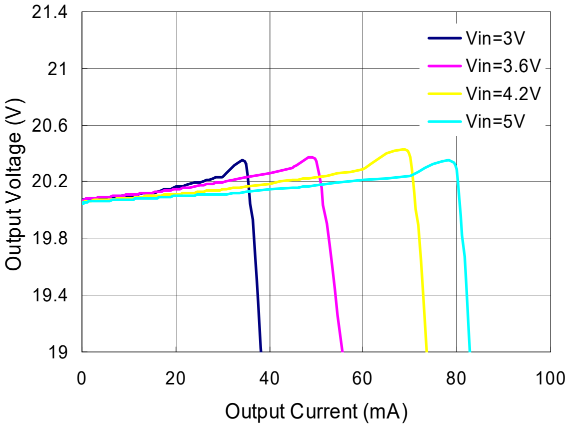
V_{OUT}=15V, L=10μH (LQH32CN100K53)



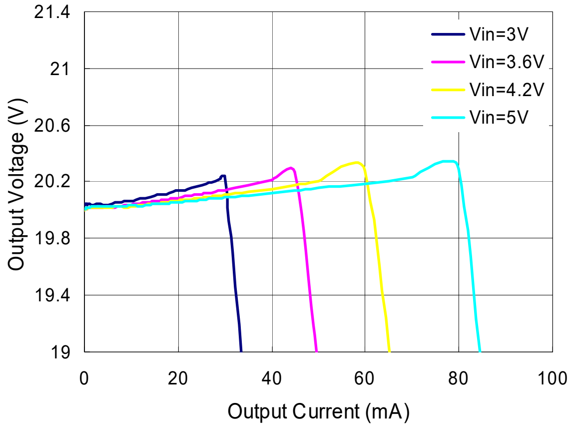
V_{OUT}=15V, L=22μH (LQH32CN220K53)



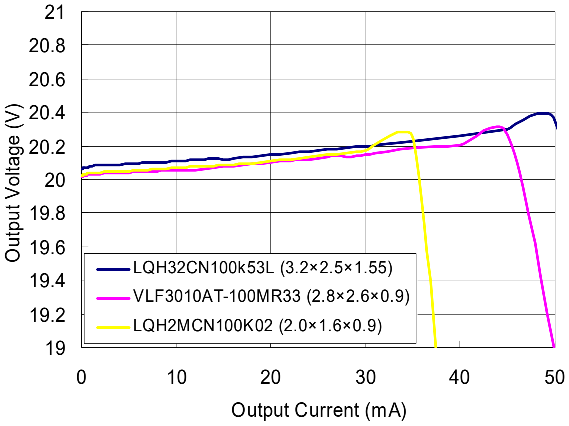
V_{OUT}=20V, L=10µH (LQH32CN100K53)



V_{OUT}=20V, L=22µH (LQH32CN220K53)

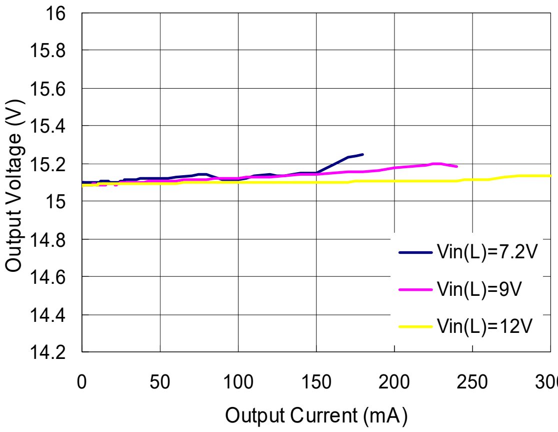


V_{OUT}=20V, V_{IN}=3.6V

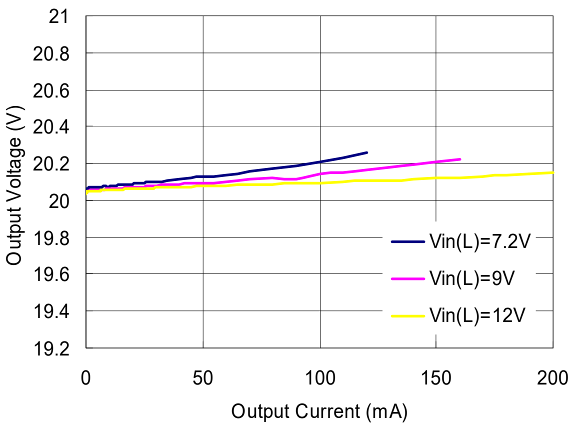


Typical Applications with Using 5.5V or Greater

VOUT=15V, L=10µH (LQH32CN100K53)

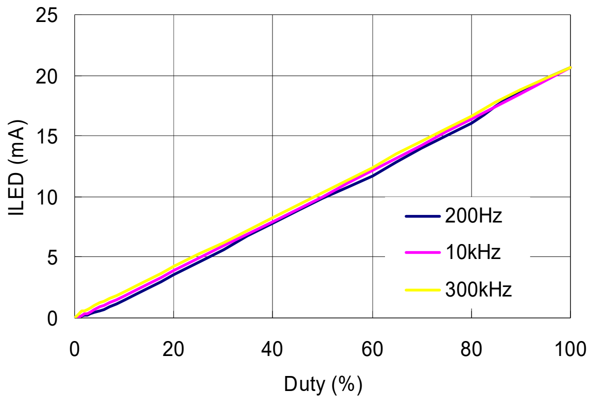


VOUT=20V, L=10µH (LQH32CN100K53)



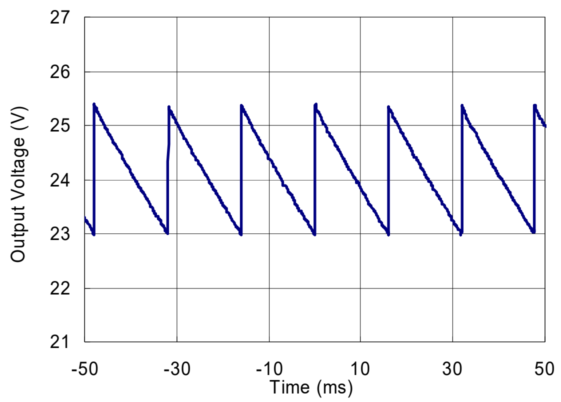
4) Duty vs. ILED

R1205N823B/C



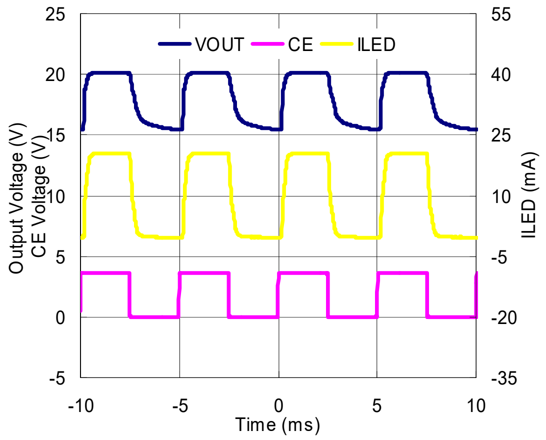
5) OVP Output Waveform

R1205N823B/C

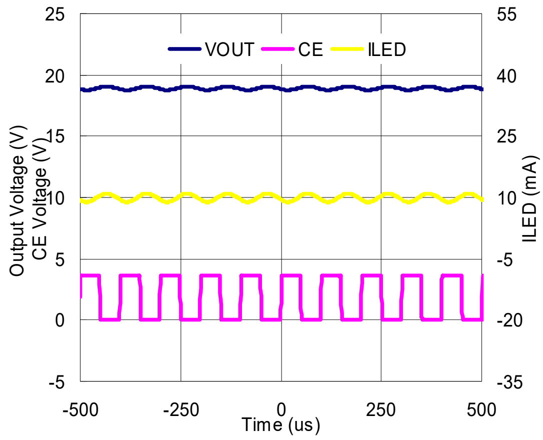


6) Waveform (6LED)

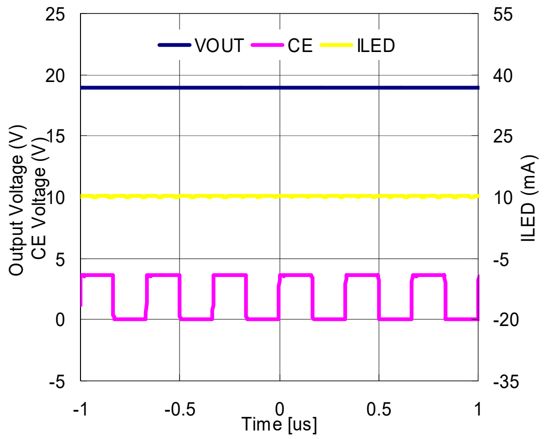
R1205N823B/C (CE Freq=200Hz)



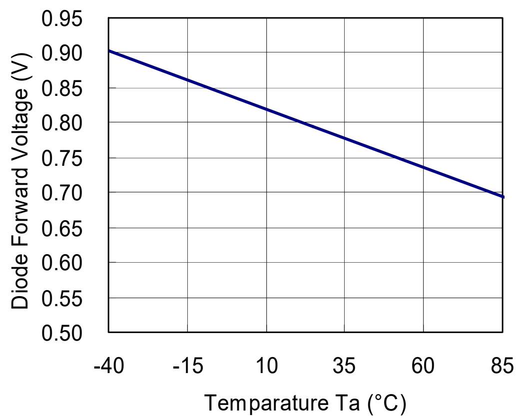
R1205N823B/C (CE Freq=10KHz)



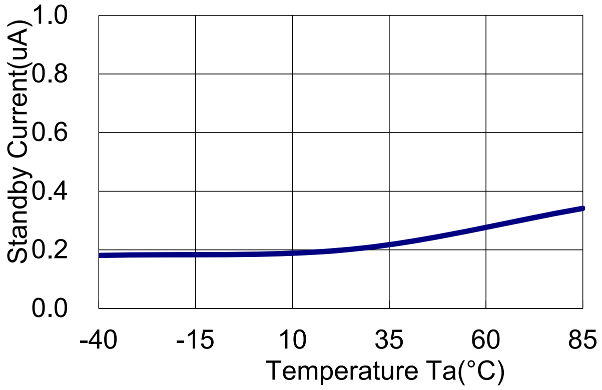
R1205N823B/C(CE Freq=300KHz)



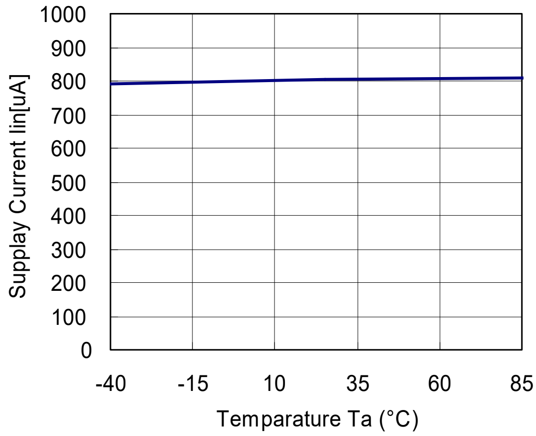
7) Diode Forward Voltage vs. Temperature



8）Standby Current vs. Temperature

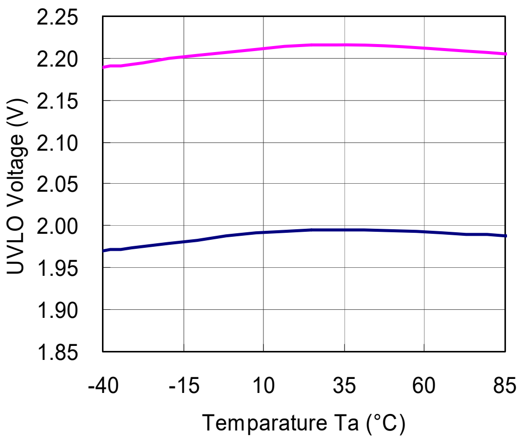


9）Supply Current vs. Temperature

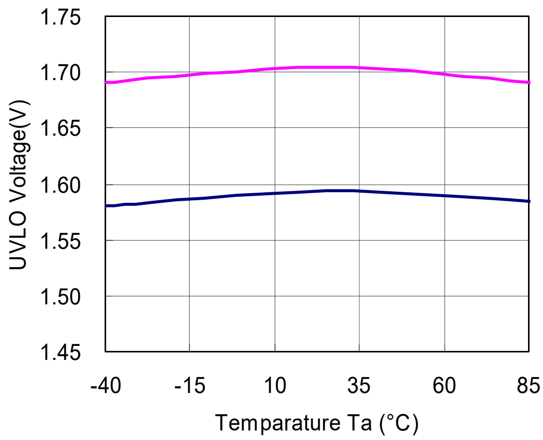


10）UVLO Output Voltage vs. Temperature

R1205x8xxA

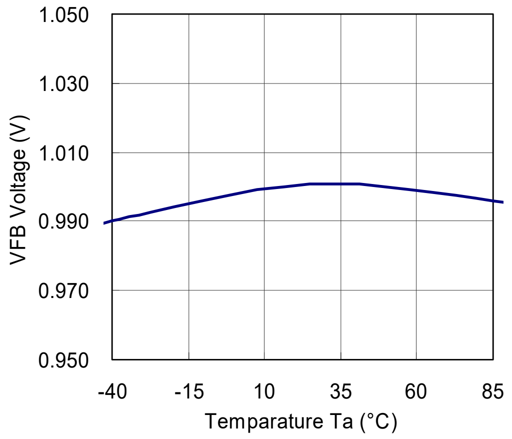


R1205x8xxB/C

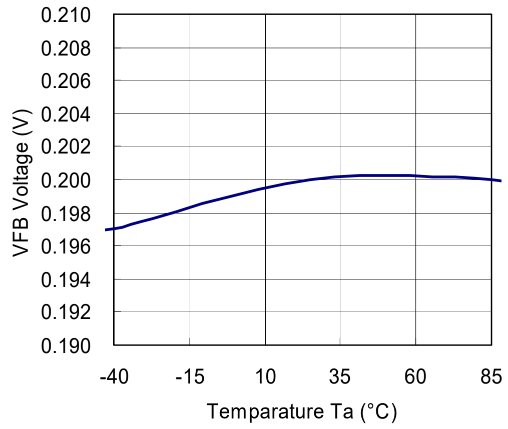


11) VFB Voltage vs. Temperature

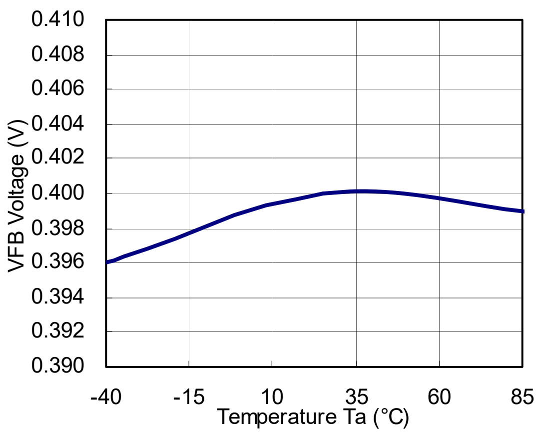
R1205x8xxA



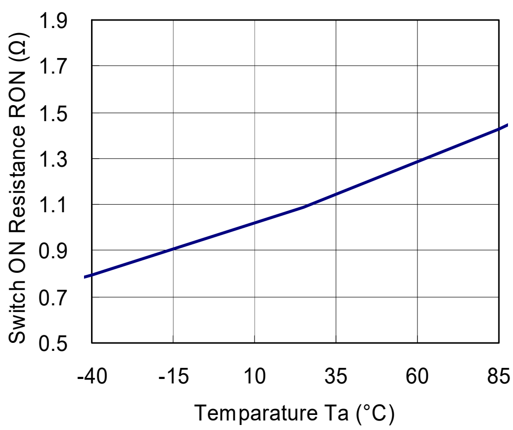
R1205x8xxB



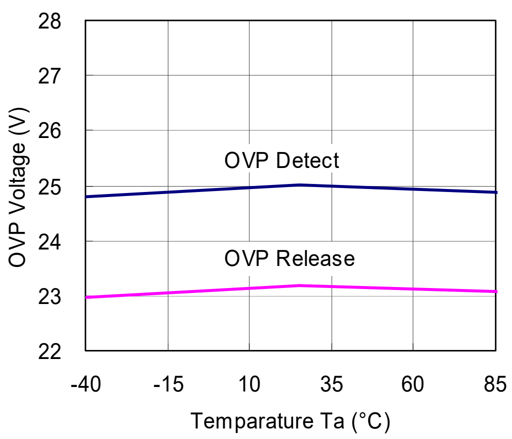
R1205x8xxC



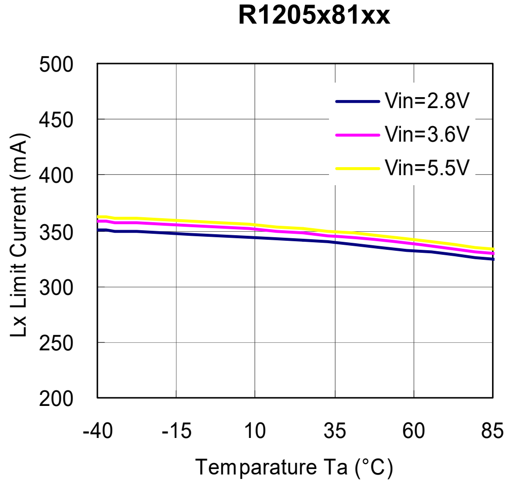
12) Switch ON Resistance RON vs. Temperature

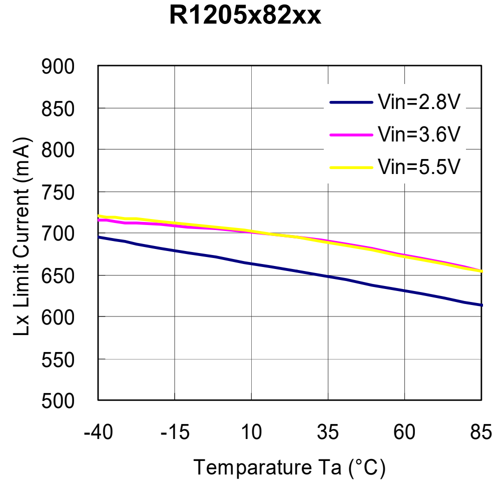


13) OVP Voltage vs. Temperature

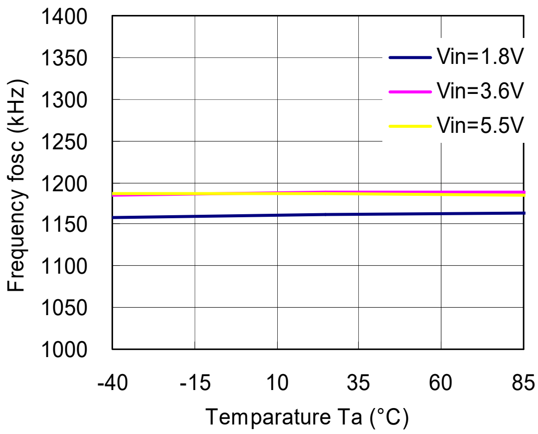


14) LX Current Limit vs. Temperature

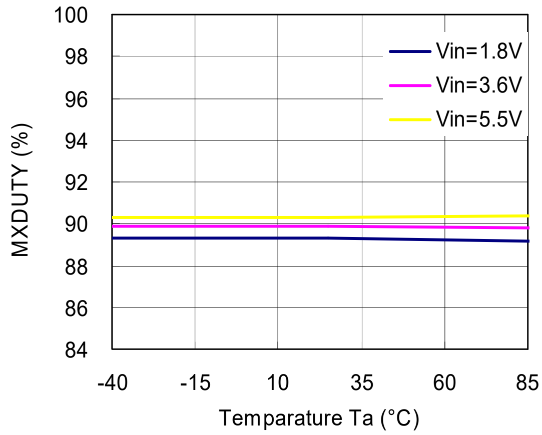




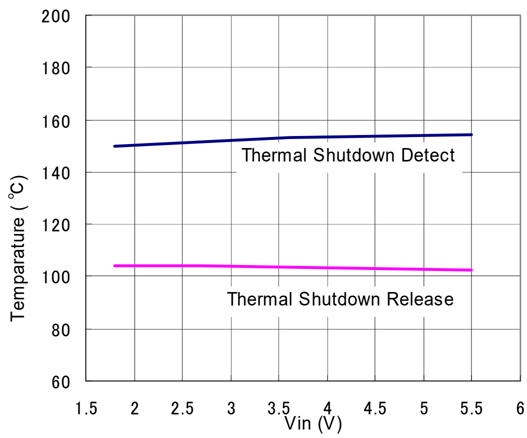
15) Oscillator Frequency vs. Temperature



16) Maxduty vs. Temperature



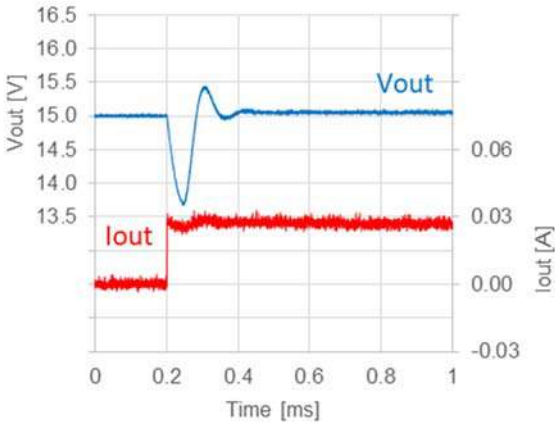
17) Thermal Shutdown Detect / Release Temperature vs. Input Voltage

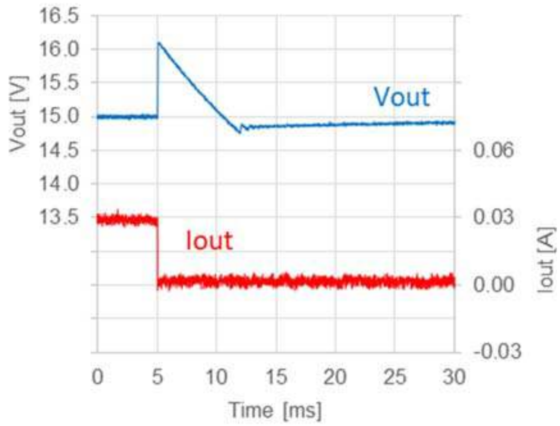


18) Load Transient Response

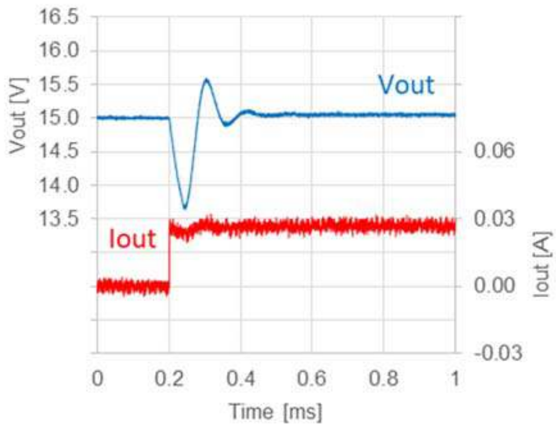
V_{IN} = 3.6 V, V_{OUT} = 15 V I_{OUT} = 0 mA ⇔ 30 mA

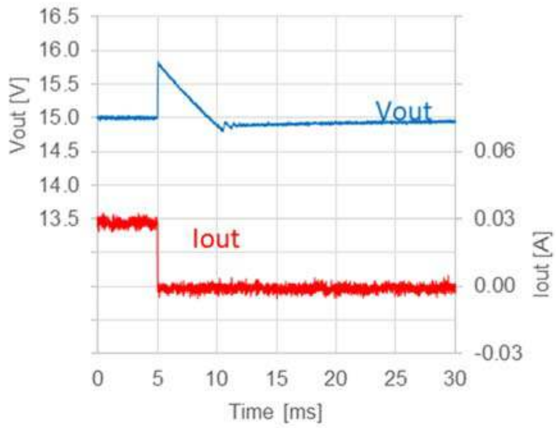
L = 10 µH Setting : Table 3-A



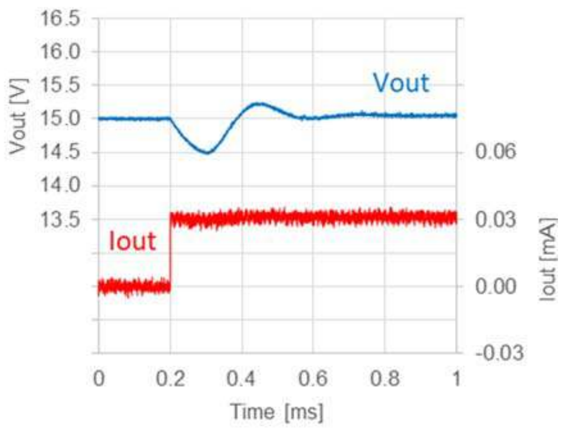


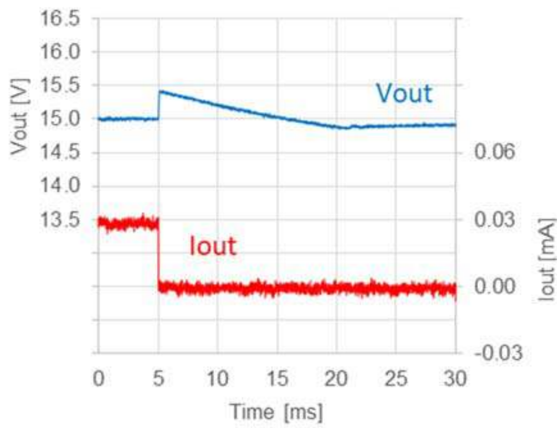
L = 22 µH Setting : Table 3-A



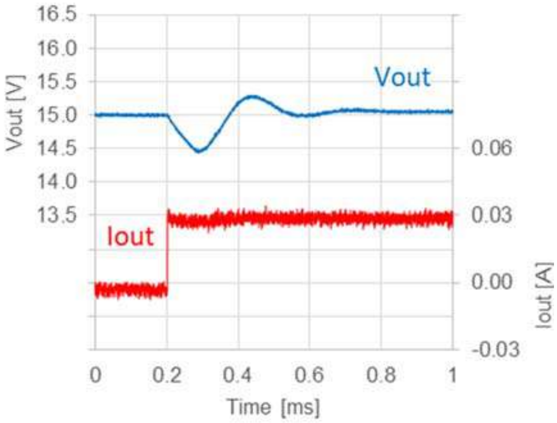


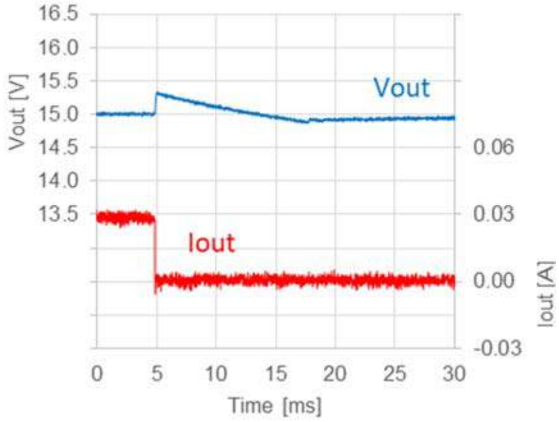
L =10 µH Setting : Table 3-B





L = 22 μH　Setting：Table 3-B





Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

Measurement Conditions

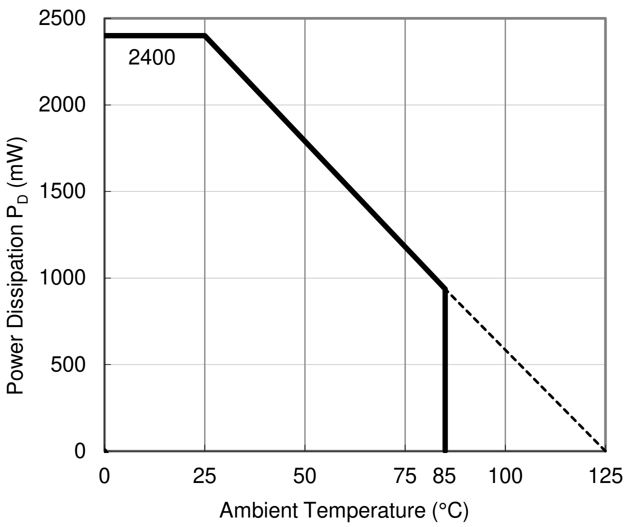
Item	Measurement Conditions (JEDEC STD. 51-7)
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	1st Layer: Less than 95% of 50 mm Square 2nd, 3rd, 4th Layers: Approx. 100% of 50 mm Square
Through-holes	ϕ 0.2 mm × 15 pcs

Measurement Result (Ta = 25°C, Tjmax = 125°C)

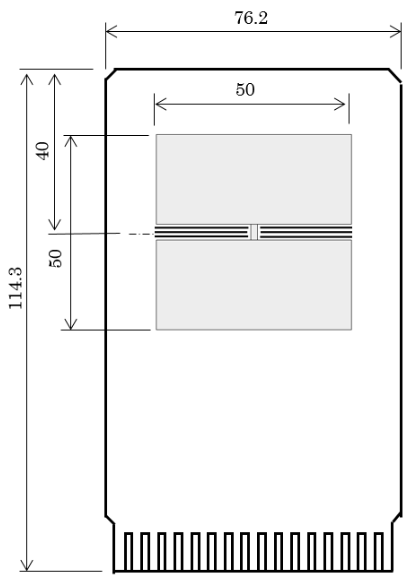
Item	Measurement Result
Power Dissipation	2400 mW
Thermal Resistance (θja)	θja = 41°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 11°C/W

θja: Junction-to–ambient thermal resistance.

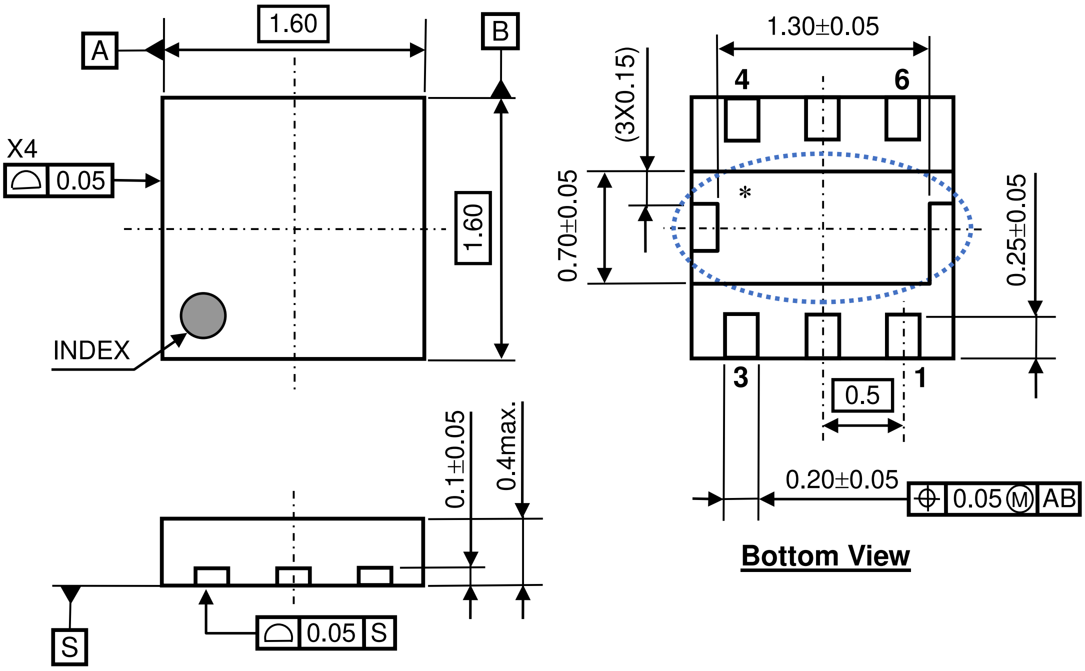
ψjt: Junction–to-top of package thermal characterization parameter.



Power Dissipation vs. Ambient Temperature



Measurement Board Pattern



DFN1616-6B Package Dimensions (Unit: mm)

* The tab on the bottom of the package shown by blue circle is a substrate potential (GND). It is recommended that this tab be connected to the ground plane pin on the board but it is possible to leave the tab floating.

Ver. A

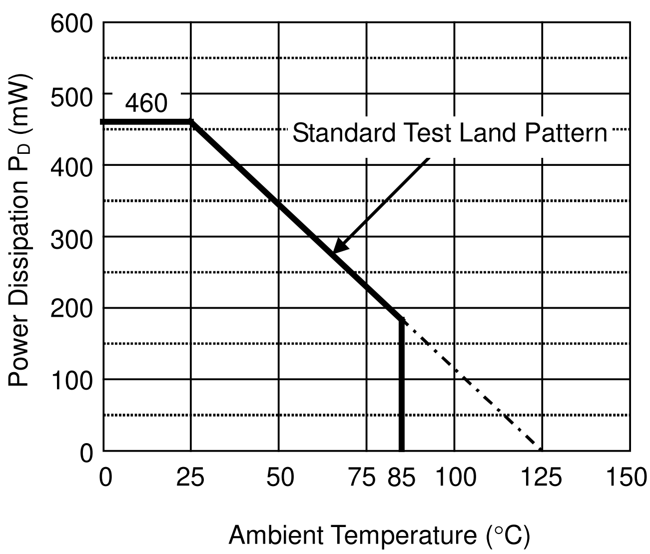
The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

Measurement Conditions

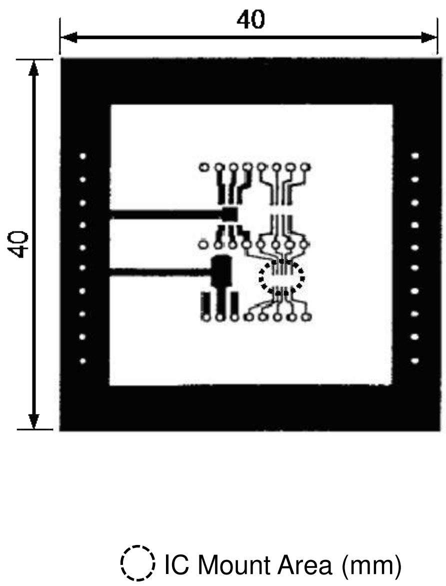
	Standard Test Land Pattern
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Double-Sided Board)
Board Dimensions	40 mm × 40 mm × 1.6 mm
Copper Ratio	Top Side: Approx. 50% Bottom Side: Approx. 50%
Through-holes	φ 0.5 mm × 44 pcs

Measurement Result (Ta = 25°C, Tjmax = 125°C)

	Standard Test Land Pattern
Power Dissipation	460 mW
Thermal Resistance	$\theta ja = (125 - 25°C) / 0.46\ W = 217°C/W$ $\theta jc = 40°C/W$

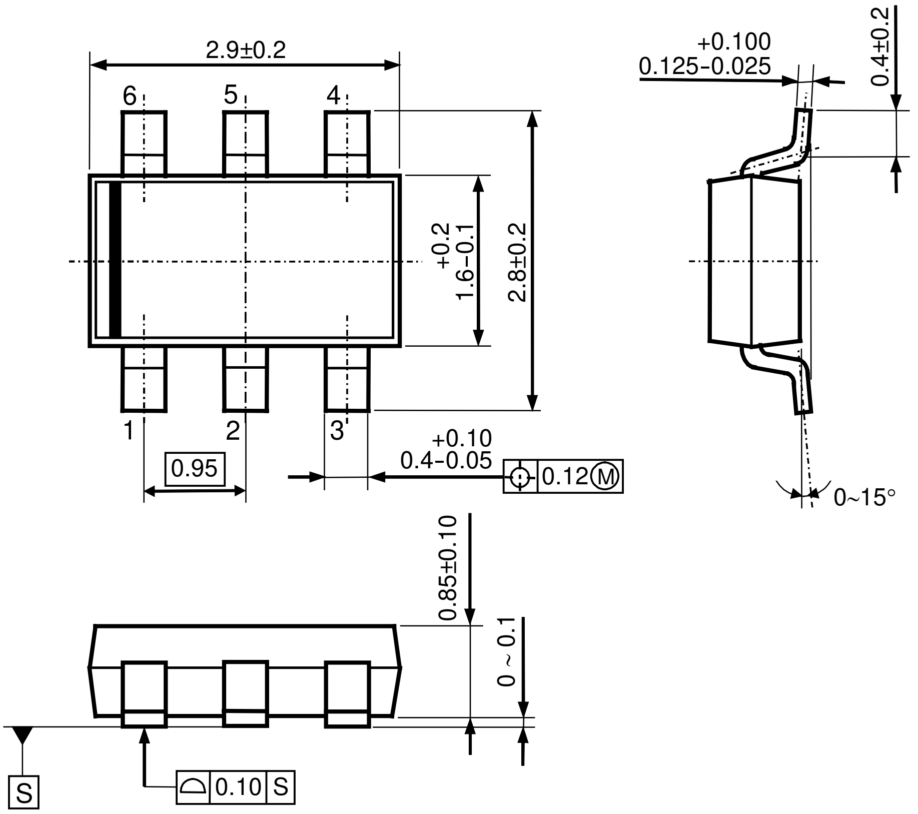


Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

Ver. A



TSOT-23-6 Package Dimensions (Unit: mm)

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7. Anti-radiation design is not implemented in the products described in this document.
8. The X-ray exposure can influence functions and characteristics of the products. Confirm the product functions and characteristics in the evaluation stage.
9. WLCSP products should be used in light shielded environments. The light exposure can influence functions and characteristics of the products under operation or storage.
10. There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact our sales or our distributor before attempting to use AOI.
11. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.

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